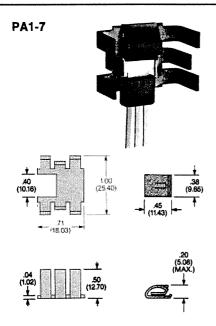
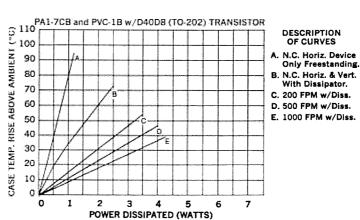


## Free-standing heat dissipator and clip assembly

- Beryllium copper clip is designed to provide high clamping pressure, which assures low thermal resistance between dissipator and semiconductor, allowing a 150% power increase in natural convection to more than 400% in forced air.
- Clip may be used alone to attach semiconductor to a customer designed heat conduction plane.
- Free-standing assembly can be mounted either vertically or horizontally on board
- requires no special tools or mounting hardware.
- Clip's spring design firmly attaches to device and dissipator, stays attached even in severe shock and vibration environments.

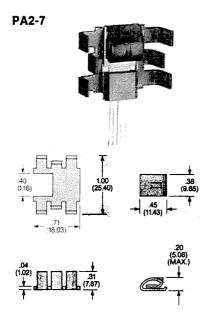


Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings.

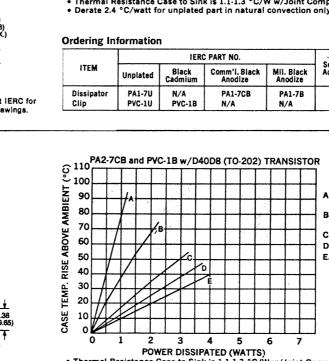


- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
  Derate 2.4 °C/watt for unplated part in natural convection only.

ITEM		IERO	0-1	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
Dissipator Clip	PA1-7U PVC-1U	N/A PVC-1B	PA1-7CB N/A	PA1-7B N/A	T0-202 T0-202	2.0 0.7



Dimensions are for reference use only. Contact IERC for dimensions with tolerances or standard part drawings



## DESCRIPTION OF CURVES

- A. N.C. Horiz. Device Only Freestanding.
- B. N.C. Horiz. & Vert. With Dissipator.
- C. 200 FPM w/Diss. D. 500 FPM w/Diss.
- E. 1000 FPM w/Diss.
- Thermal Resistance Case to Sink is 1.1-1.3 °C/W w/Joint Compound.
  Derate 2.4 °C/watt for unplated part in natural convection only.

## **Ordering Information**

ITEM		IER	C	Max.		
	Unplated	Black Cadmium	Comm'l. Black Anodize	Mil. Black Anodize	Semiconductor Accommodated	Weight (Grams)
Dissipator Clip	PA2-7U PVC-1U	N/A PVC-1B	PA2-7CB N/A	PA2-7B N/A	T0-202 T0-202	1.5 0.7